



Final Product Change Notification

201509011F01

Issue Date: 14-Sep-2015
Effective Date: 28-Dec-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online



QUALITY

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Introduction of New Clips CD0S and LCD0S for max die Trench 6 in LFPAK and LFPAK2.

Details of this Change

CD0S and LCD0S are new clip designs to be introduced for use in max die LFPAK SOT669 and LFPAK2 SOT1023 respectively. These new clip designs have a streamlined source area outline and incorporates slots within the clip source area for added stress relief and better top solder control. For the LFPAK SOT669 product types in this notification, the solder material will change from PbSn to PbSnAg for standardization.

Please see attached self qualification report.

Why do we Implement this Change

Improved product quality and reliability.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 28-Dec-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 14-Oct-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

e-mail address powermos.pcn@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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